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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10034827	FILING DATE 01/03/2002	CLASS 351	SUBCLASS 257 724	GAU 2835	EXAMINER TA/Hett Mitchell
**APPLICANTS: Morrison Gary; Edwards Darwin; Stark Leslie;					
**CONTINUING DATA VERIFIED: THIS APPLN CLAIMS BENEFIT OF 60/258,525 12/28/2000					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO TI-31373	
TITLE : Chip-scale packages stacked on folded interconnector for vertical assembly on substrates <small>U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L/Rev. 12-94</small>					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Assistant Examiner	
		Primary Examiner	
PREPARED FOR ISSUE		Application Examiner	
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